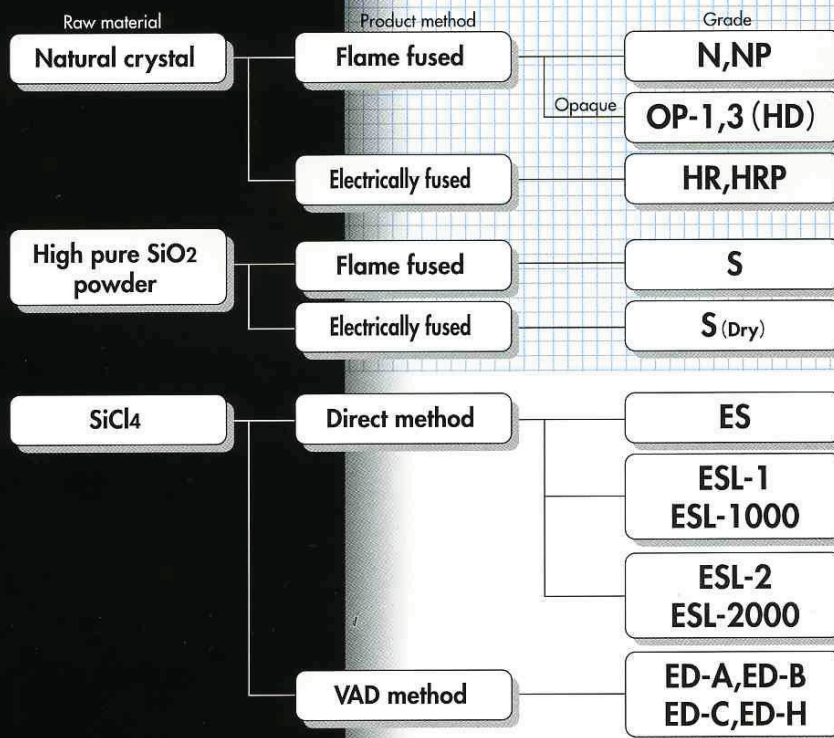


TOSOH

Quartz Materials



TOSOH

■ Fused Silica Glass (N,OP,HR Grades)

- TOSOH fused silica glasses are manufactured from SiO₂ powder in an oxy-hydrogen flame or electric furnace.
- TOSOH fused silica glasses have good heat resistance and are used to produce items for semiconductor manufacturing.
- OP-1 and OP-3 offer excellent heat and UV-IR blocking.

■ Ultra high purity fused silica glass (S Grade)

- S grade is an ultra high purity fused silica glass manufactured from high purity silica powder in an oxy-hydrogen flame or electric furnace.
- S grade has few bubbles and few inclusions and has good UV transparency equivalent to synthetic fused silica glass.
- S grade has no fluorescence when UV irradiated with a low pressure Hg lamp.

■ Synthetic fused silica glass (ES,ED Grades)

- TOSOH synthetic fused silica glasses are manufactured from high purity SiCl₄ in an oxy-hydrogen flame.
- TOSOH also uses a VAD process to produce synthetic silica glasses. This then combines high purity and low OH for excellent transmission from the DUV through IR regions.
- ES grade offers excellent laser durability. ED grades offer superior heat resistance and DUV transparency.

Optical properties

| Grade | Bubble class DIN58927 | Striae ⁽¹⁾ | Homogeneity Δn ppm | Strain nm/cm | Fluorescence $\lambda=254\text{nm}$ 2mW/cm^2 | Laser durability | Radiation durability X or γ -ray | OH content ppm | Available size mm |
|----------|--------------------------|-----------------------|----------------------------------|-----------------|---|--------------------------|--|-------------------|----------------------|
| N | 0-4 | — | — | <25 | blue | — | dark brown | <200 | □1200 |
| NP | 0-4 | — | — | <25 | blue | — | dark brown | <200 | □1200 |
| S | 0-4 | — | — | <25 | None | — | dark brown | <200 | □1200 |
| ES | 0 | 1D | — | <20 | None | — | No change | 600-1300 | □700 |
| ESL-1 | 0 | 1D | <20 ($\phi 600$) | <10 | None | — | No change | 600-1300 | □700 |
| ESL-1000 | 0 | 1D | <10 ($\phi 350$) | <10 | None | Guarantee ⁽²⁾ | No change | 600-1300 | □700 |
| ESL-2 | 0 | 3D | <10 ($\phi 300$) | <10 | None | — | No change | 600-1300 | □700 |
| ESL-2000 | 0 | 3D | <10 ($\phi 300$) | <10 | None | Guarantee ⁽²⁾ | No change | 600-1300 | □700 |
| ED-A | 0 | 3D | — | <10 | None | — | No change | <200 | □400 |
| ED-B | 0 | 3D | — | <10 | None | — | No change | <10 | □400 |
| ED-C | 0 | — | — | <10 | None | — | No change | <1 | □400 |
| ED-H | 0 | 3D | <10 ($\phi 200$) | <10 | None | — | No change | <100 | □400 |

- (1) 1D: 1 direction striae free
3D: 3 direction striae free
(2) Specified with TOSOH own condition of KrF and ArF excimer laser damage tests.

Mechanical , thermal and electrical properties

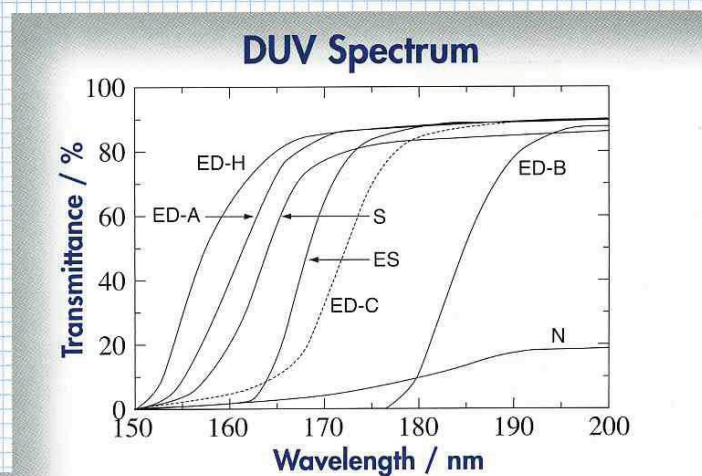
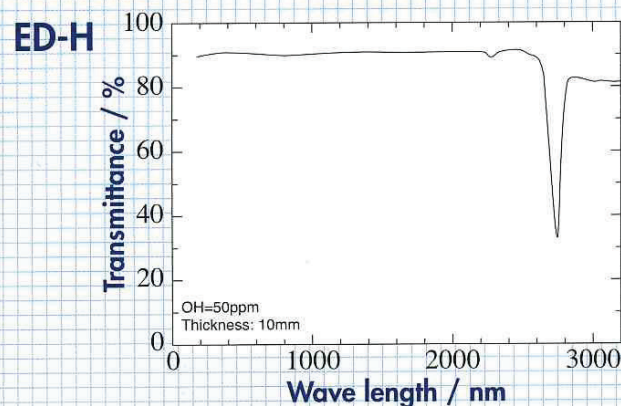
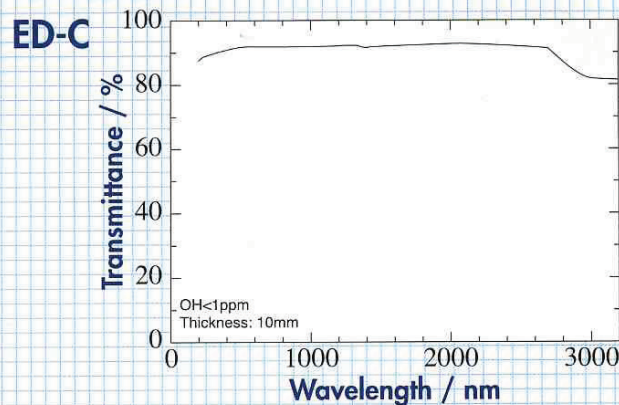
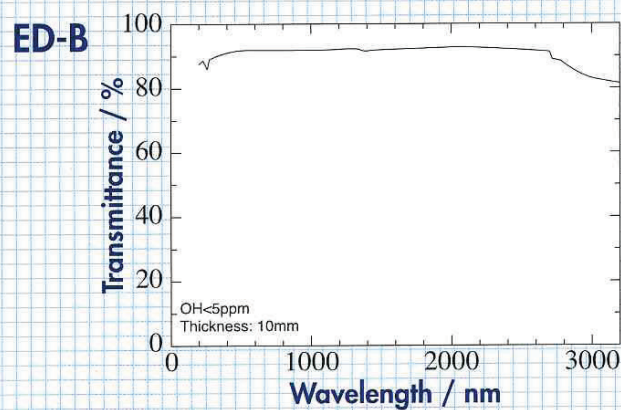
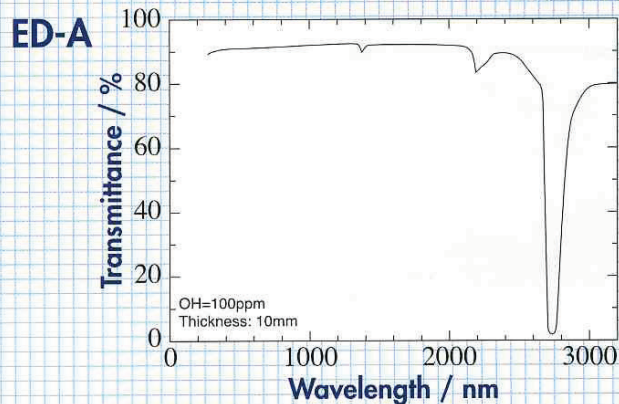
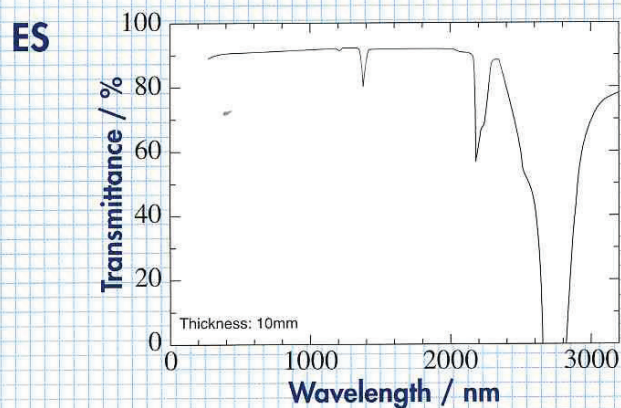
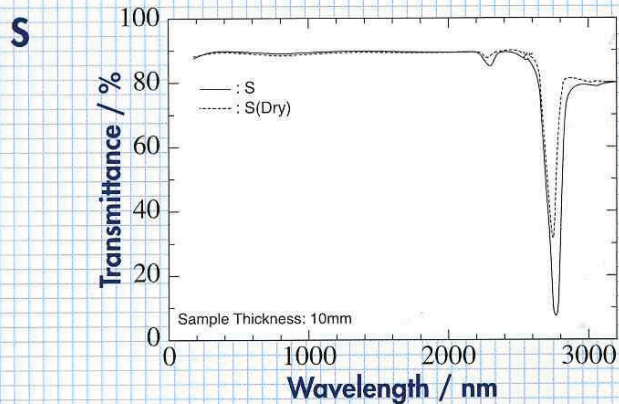
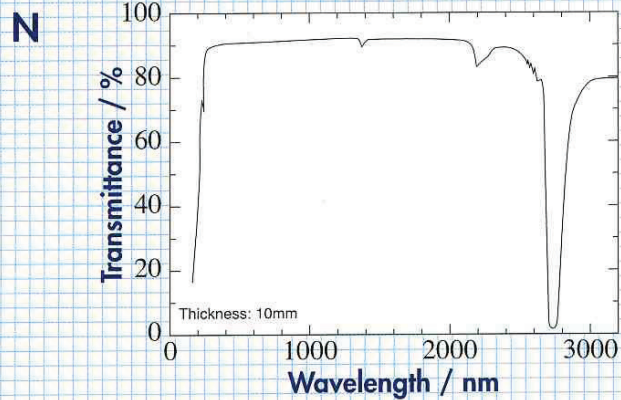
| | | | Fused quartz | | | | | | Synthetic fused silica | | | | |
|-----------------------|--|---|--------------------|--------------------|--------------------|-------|-------|--------|------------------------|--------------------|--------------------|--------------------|--------------------|
| | | | N,NP | S | HR,HRP | OP-1 | OP-3 | OP-3HD | ES | ED-A | ED-B | ED-C | ED-H |
| Mechanical properties | Density | g cm^{-3} | 2.2 | 2.2 | 2.2 | 2.02 | 2.02 | 2.1 | 2.2 | 2.2 | 2.2 | 2.2 | 2.2 |
| | Vickers hardness | MPa | 8,900 | 8,900 | 8,900 | 8,900 | 8,900 | 8,900 | 8,900 | 8,900 | 8,900 | 8,900 | 8,900 |
| | Young's modulus | GPa | 74 | 74 | 74 | | | | 74 | 74 | 74 | 74 | 74 |
| | Shear modulus | GPa | 31 | 31 | 31 | | | | 31 | 31 | 31 | 31 | 31 |
| | Poisson's ratio | | 0.17 | 0.17 | 0.17 | | | | 0.18 | 0.18 | 0.18 | 0.18 | 0.18 |
| | Bending strength | MPa | 94.3 | 94.3 | 94.3 | 60 | 60 | 67 | 94.3 | 94.3 | 94.3 | 94.3 | 94.3 |
| | Compressive strength | MPa | 1130 | 1130 | 1130 | | | | 1130 | 1130 | 1130 | 1130 | 1130 |
| | Tensile strength | MPa | 49 | 49 | 49 | | | | 49 | 49 | 49 | 49 | 49 |
| Thermal properties | Torsion strength | MPa | 29 | 29 | 29 | | | | 29 | 29 | 29 | 29 | 29 |
| | Strain point | °C | 1,070 | 1,060 | 1,120 | 1,050 | 1,050 | 1,050 | 970 | 1,060 | 1,110 | 970 | 1,060 |
| | Annealing point | °C | 1,180 | 1,165 | 1,220 | 1,170 | 1,170 | 1,170 | 1,080 | 1,170 | 1,200 | 1,080 | 1,170 |
| | Softening point | °C | 1,720 | 1,720 | 1,720 | 1,720 | 1,720 | 1,720 | 1,720 | 1,720 | 1,720 | 1,720 | 1,720 |
| | Coefficient of thermal expansion | $\times 10^{-6} \text{ } ^\circ\text{C}^{-1}$ | 5.9 | 5.9 | 5.9 | 6.9 | 6.9 | 6.9 | 4.7 | 4.7 | 4.7 | 4.7 | 4.7 |
| | Specific heat (at 20°C) | $\text{J kg}^{-1} \text{K}^{-1}$ | 749 | 749 | 749 | 749 | 749 | 749 | 749 | 749 | 749 | 749 | 749 |
| | Thermal diffusivity (at 19°C) | $\times 10^{-6} \text{ m}^2 \text{ s}^{-1}$ | 8.3 | 8.3 | 8.3 | 8.4 | 8.4 | 8.5 | 8.5 | 8.5 | 8.5 | 8.5 | 8.5 |
| | Thermal conductivity (at 19°C) | $\text{W m}^{-1} \text{K}^{-1}$ | 1.38 | 1.38 | 1.38 | 1.24 | 1.24 | 1.33 | 1.38 | 1.38 | 1.38 | 1.38 | 1.38 |
| Electrical properties | Viscosity ($\log \eta$, 1200°C) | Pa s | 11.72 | 11.10 | 12.18 | 11.72 | 11.72 | 11.72 | 10.6 | 11.61 | 12.00 | 10.6 | 11.37 |
| | Dielectric constant (ϵ' , 500MHz) | | 3.9 | 3.9 | 3.9 | 3.7 | 3.7 | 3.8 | 3.9 | 3.9 | 3.9 | 3.9 | 3.9 |
| | Dielectric loss factor ($\tan \delta$, 500MHz) | $\times 10^{-3}$ | <1 | <1 | <1 | <1 | <1 | <1 | <1 | <1 | <1 | <1 | <1 |
| | Resistivity (at 25°C) | Ω | 3×10^{15} | 4×10^{15} | 8×10^{15} | | | | 5×10^{15} | 3×10^{15} | 4×10^{15} | 8×10^{15} | 8×10^{15} |
| | Volume resistivity (at 25°C) | $\Omega \cdot \text{cm}$ | 5×10^{16} | 7×10^{16} | 1×10^{17} | | | | 1×10^{17} | 5×10^{16} | 7×10^{16} | 1×10^{17} | 5×10^{17} |

Purity

| | | Al | Ca | Cu | Fe | Na | K | Li | Mg | OH |
|------------------------|-----------|-------|-------|-------|-------|-------|-------|-------|-------|------|
| Fused quartz | N | 8 | 0.6 | <0.01 | 0.2 | 0.6 | 0.1 | <0.01 | 0.04 | 200 |
| | NP | 7 | 0.5 | <0.01 | 0.1 | 0.1 | 0.03 | <0.01 | 0.02 | 200 |
| | S | 0.7 | <0.01 | <0.01 | 0.05 | 0.1 | <0.01 | <0.01 | <0.01 | 160 |
| | S (Dry) | 0.04 | <0.01 | <0.01 | 0.08 | 0.02 | <0.01 | <0.01 | <0.01 | 50 |
| | OP-1 | 8 | 0.7 | <0.01 | 0.2 | 0.5 | 0.3 | 0.07 | 0.04 | 160 |
| | OP-3 (HD) | 7 | 0.6 | <0.01 | 0.07 | 0.06 | 0.03 | 0.07 | 0.02 | 160 |
| Synthetic fused silica | ES | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | 1000 |
| | ED-A | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <200 |
| | ED-B | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <10 |
| | ED-C | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <1 |
| | ED-H | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <0.01 | <100 |

Unit:ppm

Spectrum UV-IR, DUV



Handling Precautions

■ Devitrification

When silica glass is exposed to high temperatures, the pure SiO_2 structure changes from a glass state (amorphous) to a stable crystalline state called cristobalite. This structural change is known as devitrification and generally occurs at temperatures of over $1,150^\circ\text{C}$ for clean clear fused quartz. Devitrification may also occur at temperatures of less than $1,000^\circ\text{C}$ if impurity exist, e.g. metal.

The relation between devitrification rate of clear fused quartz and temperatures in various atmospheres is as follows.

| Gas composition | Temperature $^\circ\text{C}$ | Time h | Degree of devitrification | Devitrification thickness μm |
|---|---------------------------------|-----------|--|--|
| Air | 1,300 | 72 | surface perfectly devitrificated | 250 |
| Dried Oxygen | 1,300 | 72 | devitrification for 50% of all surface | 100~150 |
| Industrial Nitrogen | 1,300 | 72 | surface devitrificated | — |
| Nitrogen (removed O_2 and H_2O) | 1,300 | 72 | no devitrification | — |
| Hydrogen (removed O_2 and H_2O) | 1,300 | 72 | no devitrification | — |

■ Handling Precautions

Care must be taken to avoid direct hand contact of fused silica. Skin's natural salts contain alkali metal elements such as sodium, potassium along with other impurities that cause accelerated devitrification. Source of metal contaminants should also be avoided.

For precaution, fused silica should be washed in pure or distilled water, then either air dried in a clean area or wiped dry with an alcohol wetted clean cloth. For more rigorous cleaning, a very thin outer layer of the glass can be removed by etching, prior to water washing, in a 5-10% Hydrofluoric acid solution.

■ Usage Precautions

- Always clean fused silica prior to use.
- Dry product completely before using at high temperature.
- Pay attention to devitrification due to atmosphere exposure.
- Although fused silica can resist sudden heating and quenching, it does have its limits. Please refer to the thermal properties for your application.
- Fused silica's very low thermal expansion must be considered when the glass is used with other materials to avoid failure due to the difference in thermal expansion.
- Caution should be taken during prolonged usage at temperature approaching the yield point.
- Gradual structural deformation may occur due to the lower viscosity.



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